SCDS031I - MAY 1996 - REVISED OCTOBER 2000

PACKAGE

- Members of Texas Instruments' Widebus™ Family
- Standard '16244-Type Pinout
- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels

description

The 'CBT16244 devices provide 16 bits of high-speed TTL-compatible bus switching in a standard '16244 device pinout. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

These devices are organized as four 4-bit low-impedance switches with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the switch is on, and data can flow from port A to port B, or vice versa. When \overline{OE} is high, the switch is open, and the high-impedance state exists between the two ports.

SN74CBT16244		,	
	,	,	
2B3 2B4 3B1 3B2 GND 3B3 3B4 V _{CC} 4B1 4B2 GND 4B3 4B4 4OE	12 13 14 15 16 17 18 19 20 21 22 23 24	37 2A4 36 3A1 35 3A2 34 GND 33 3A3 32 3A4 31 V _{CC} 30 4A1 29 4A2 28 GND 27 4A3 26 4A4 25 3OE	

ORDERING INFORMATION

TA	PACKA	GEŤ	ORDERABLE PART NUMBER	TOP-SIDE MARKING		
–40°C to 85°C	SSOP – DL	Tube	SN74CBT16244DL	CBT16244		
	330F - DL	Tape and reel	SN74CBT16244DLR	CB110244		
-40 C 10 65 C	TSSOP – DGG	Tape and reel	SN74CBT16244DGGR	CBT16244		
	TVSOP – DGV	Tape and reel	SN74CBT16244DGVR	CY244		
–55°C to 125°C	CFP – WD	Tube	SNJ54CBT16244WD	SNJ54CBT16244WD		

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUN	ICTIC	DN T	ABLE
(each	4-bit	bus	switch)

INPUT OE	OUTPUTS A, B
L	A port = B port
н	Disconnect



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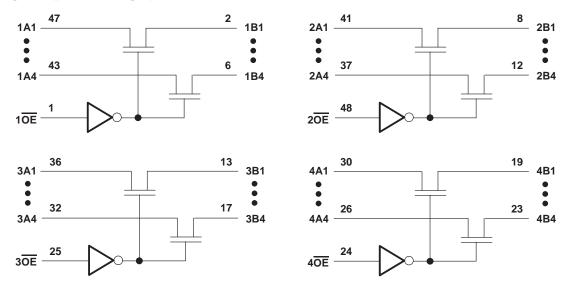
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}		–0.5 V to 7 V
Input voltage range, V _I (see Note 1)		–0.5 V to 7 V
Continuous channel current		128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)		–50 mA
Package thermal impedance, θ_{JA} (see Note 2):	DGG package	70°C/W
	DGV package	58°C/W
	DL package	63°C/W
Storage temperature range, T _{stg}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed. 2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		SN54CB	T16244	SN74CB	T16244	UNIT
		MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage	4	5.5	4	5.5	V
VIH	High-level control input voltage	2		2		V
VIL	Low-level control input voltage		0.8		0.8	V
TA	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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	METER	TEAT OOL			SN5	4CBT16	244	SN7	4CBT16	244	
PARA	METER	TEST CON	IDITIONS		MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT
VIK		V _{CC} = 4.5 V,	lj = -18 mA				-1.2			-1.2	V
1.		VCC = 0	VI = 5.5 V				10			10	A
łı		V _{CC} = 5.5 V	V _I = 5.5 V or	GND			±1			±1	μA
ICC		$V_{CC} = 5.5 V,$ $V_{I} = V_{CC} \text{ or GND}$	IO = 0,				3.2	i		3	μA
ΔI_{CC}^{\ddagger}	Control inputs	$V_{CC} = 5.5 V$, Other inputs at V_{CC} or GND	One input at	3.4 V,			2.5			2.5	mA
Ci	Control inputs	$V_{I} = 3 V \text{ or } 0$				2.5			2.5		pF
Cio(OFI	 F)	V _O = 3 V or 0,	$\overline{OE} = V_{CC}$			4.5			4.5		рF
		$V_{CC} = 4 V,$	V _I = 2.4 V,	l _l = 15 mA			20			20	
r _{on} §			$V_{I} = 0,$	l _l = 64 mA		5	10		5	7	
ona		$V_{CC} = 4.5 V$	$V_{ } = 0,$	l _l = 30 mA		5	10		5	7	Ω
			V _I = 2.4 V,	lj = 15 mA		8	14		8	12	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. [‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

§ Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

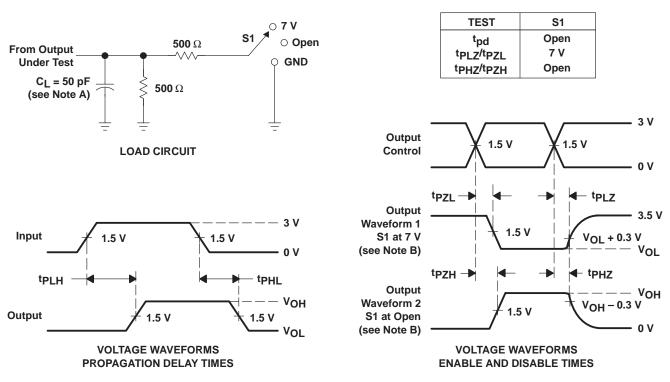
Γ	PARAMETER		то (оитрит)		SN54CB	T16244						
		FROM (INPUT)		V _{CC} = 4 V		V _{CC} = 5 V ± 0.5 V		V _{CC} = 4 V		V _{CC} = 5 V ± 0.5 V		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
Γ	t _{pd} ¶	A or B	B or A				0.8*		0.35		0.25	ns
Γ	ten	OE	A or B		10.3	1	9.2		5.5	1	5.1	ns
	^t dis	OE	A or B		9.7	1	8.2		5.2	1	5.4	ns

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).



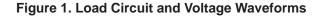
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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
 Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .







PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead finish/	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	Ball material	(3)		(4/5)	
							(6)				
SN74CBT16244DGGR	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT16244	Samples
SN74CBT16244DL	ACTIVE	SSOP	DL	48	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT16244	Samples
SN74CBT16244DLR	ACTIVE	SSOP	DL	48	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT16244	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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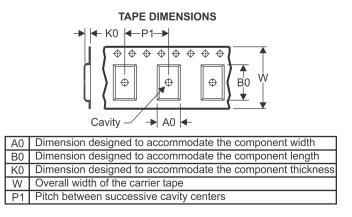
PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



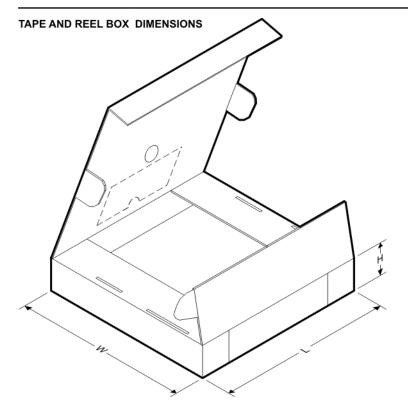
*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CBT16244DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74CBT16244DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1



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PACKAGE MATERIALS INFORMATION

24-Apr-2022



*All dimensions are nominal

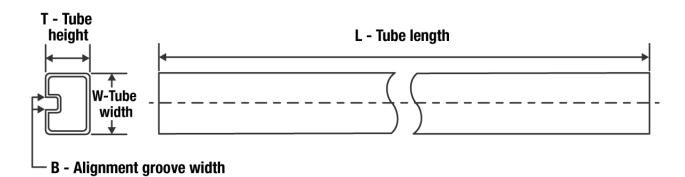
Device	Package Type	ype Package Drawing		SPQ	Length (mm)	Width (mm)	Height (mm)	
SN74CBT16244DGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0	
SN74CBT16244DLR	SSOP	DL	48	1000	367.0	367.0	55.0	



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24-Apr-2022

TUBE

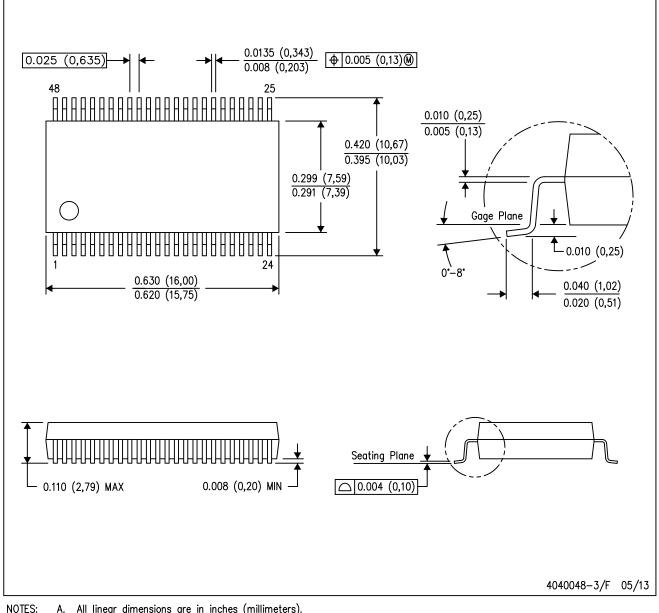


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
SN74CBT16244DL	DL	SSOP	48	25	473.7	14.24	5110	7.87

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

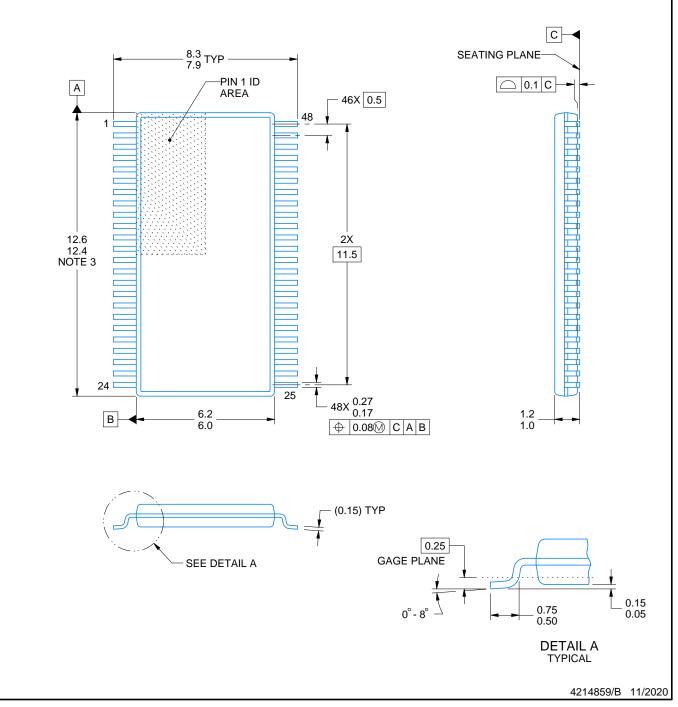
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PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
 This drawing is subject to change without notice.
 This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not

- exceed 0.15 mm per side. 4. Reference JEDEC registration MO-153.



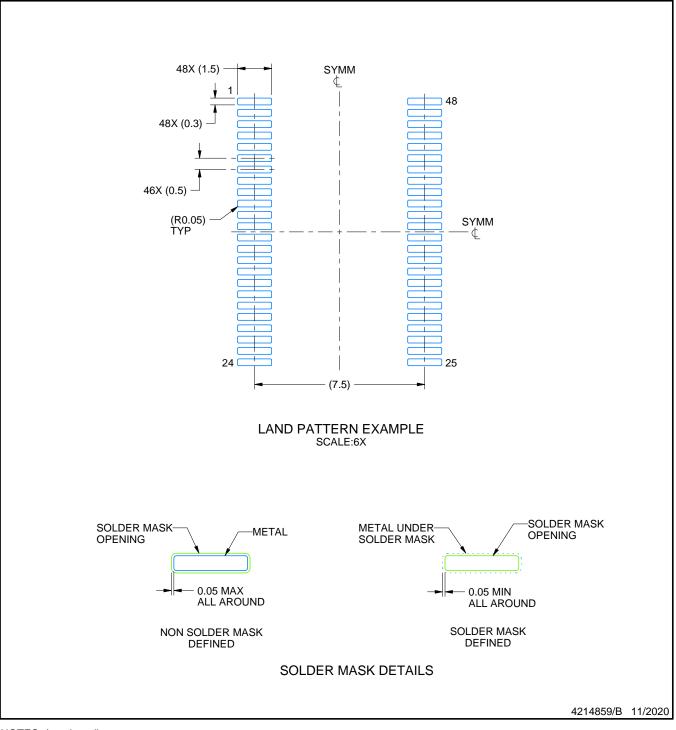
DGG0048A

DGG0048A

EXAMPLE BOARD LAYOUT

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

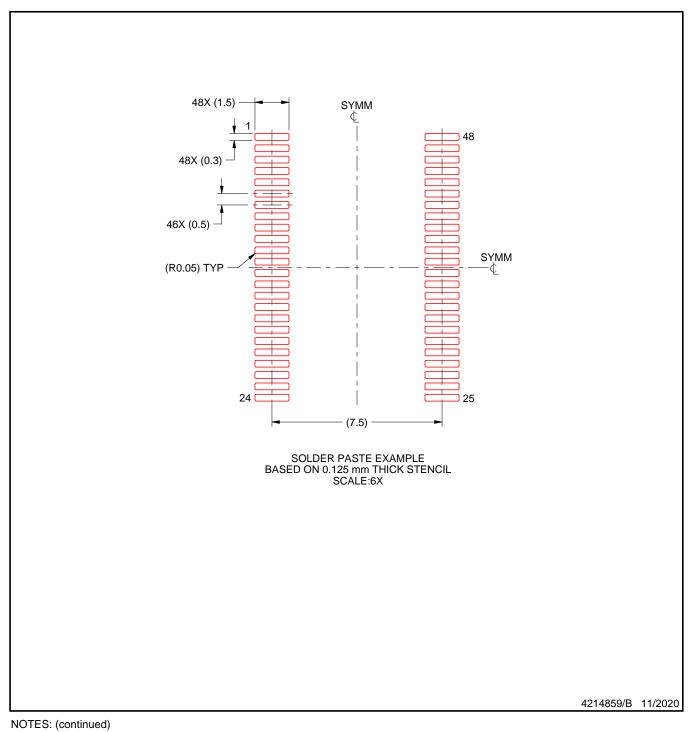


DGG0048A

EXAMPLE STENCIL DESIGN

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate

design recommendations. 8. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

MTSS003D - JANUARY 1995 - REVISED JANUARY 1998

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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